Electronic Pat	ent App	olication Fee	Transmit	tal			
Application Number:	10	10620002					
Filing Date:	14	14-Jul-2003					
Title of Invention:	SE	SLURRY FOR USE WITH FIXED-ABRASIVE POLISHING PADS IN POLISHING SEMICONDUCTOR DEVICE CONDUCTIVE STRUCTURES THAT INCLUDE COPPER AND A COPPER BARRIER					
First Named Inventor/Applicant Name:	Dir	Dinesh Chopra					
Filer:	Bri	Brick Glenn Power/Sharley Thayne					
Attorney Docket Number:	22	2269-4373.2US (00-0036.02					
Filed as Large Entity							
Utility under 35 USC 111(a) Filing Fees							
Description		Fee Code	Quantity	Amount	Sub-Total in USD(\$)		
Basic Filing:							
Pages:				A			
Claims:							
Claims in excess of 20		1202	4	52	208		
Miscellaneous-Filing:							
Petition:							
Patent-Appeals-and-Interference:							
Post-Allowance-and-Post-Issuance:							
Extension of Times							

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Miscellaneous:				
	Total in USD (\$)			208